

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-5 (Canceled).

Claim 6 (Original): A semiconductor device comprising:

a metal block having a first surface and a second surface opposite to said first surface;

a semiconductor element joined to said first surface of said metal block through a jointing material;

a resin insulating layer having a third surface and a fourth surface opposite to said third surface, said third surface being joined to said second surface of said metal block; and

a resin package for sealing said metal block and said semiconductor element, wherein said fourth surface of said resin insulating layer is exposed, and said resin insulating layer has an elasticity higher than that of said resin package.

Claim 7 (Original): The semiconductor device according to claim 6, wherein said resin insulating layer is made of a silicon resin including a ceramic material for filling said silicon resin.

Claim 8 (Original): The semiconductor device according to claim 6, wherein said metal block is provided per insulation unit of said semiconductor element.

Application No.: 09/895,025

Reply to Office Action of November 17, 2004

Claim 9 (Previously Presented): The semiconductor device according to claim 6, wherein said metal block includes a surface having a region larger than a surface of said jointing material on a side opposite to said jointing material, said surface of said jointing material lying on a side opposite to said semiconductor element.

Claim 10 (Original): The semiconductor device according to claim 6, wherein a gap between said metal block and said semiconductor element becomes wider as a distance from a center of said semiconductor element becomes longer; and said gap is filled with said jointing material.

Claim 11 (Canceled).